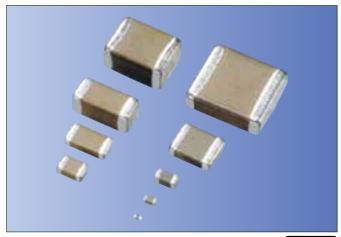
### **Multilayer Ceramic Chip Capacitors**



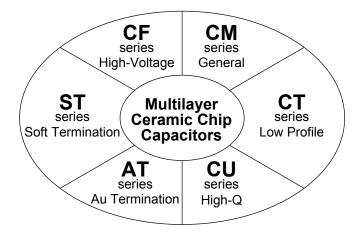
Kyocera's series of Multilayer Ceramic Chip Capacitors are designed to meet a wide variety of needs. We offer a complete range of products for both general and specialized applications, including CM series for general-purpose, CT series for low profile, CU series for Hi-Q, AT series for Au termination, ST series for soft termination, and CF series for high-voltage.

#### **Features**

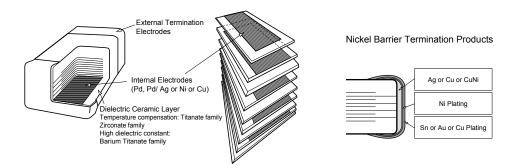
- We have a network worldwide in order to supply our global customer bases quickly and efficiently and to maintain our reputation as one of the highest-volume producers in the industry.
- All our products are highly reliable due to their monolithic structure of high-purity and superfine uniform ceramics and their integral internal electrodes.
- By combining superior manufacturing technology and materials with high dielectric constants, we produce extremely compact components with exceptional specifications.
- Our stringent quality control in every phase of production from material procurement to shipping ensures consistent manufacturing and super quality.
- Kyocera components are available in a wide choice of dimensions, temperature characteristics, rated voltages, and terminations to meet specific configurational requirements.



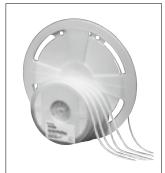




#### **Structure**



#### **Tape and Reel**



Please contact your local AVX, Kyocera sales office or distributor for specifications not covered in this catalog.

Our products are continually being improved. As a result, the capacitance range of each series is subject to change without notice. Please contact an sales representative to confirm compatibility with your application.

## **Multilayer Ceramic Chip Capacitors**



Kyocera Ceramic Chip Capacitors are available for different applications as classified below:

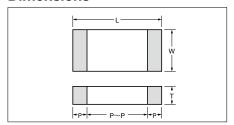
Series	Dielectric Options	Typical Applications	Features	Terminations	Available Size
СМ	C0G (NP0) X5R X7R *X6S X7S	General purpose	Wide cap range	Nickel barrier/ Tin	01005, 0201, 0402 0603, 0805, 1206 1210, 1812
СТ	X5R X7R	Module / Memory card	Low profile	Nickel barrier/ Tin	0201, 0402, 0603 0805, 1206, 1210
си	COG (NP0)	Power amplifier	High-Q	Nickel barrier/ Tin	01005
AT	X5R X7R	Optical communications	Au termination	Nickel barrier/ Au	0201, 0402
ST	X5R X7R X7S	PCB with severe bending conditions	Soft termination	Nickel barrier/ Tin (Soft Termination)	0201, 0402
CF	C0G (NP0) X7R	High voltage & Power circuits	High voltage 250Vdc, 630Vdc 1000Vdc, 2000Vdc 3000Vdc, 4000Vdc	Nickel barrier/ Tin	0805, 1206, 1210 1808, 1812, 2208 2220

<sup>\*</sup> Option
\* Negative temperature coefficient dielectric types are available on request.

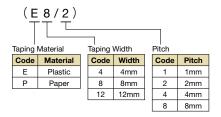
## **Multilayer Ceramic Chip Capacitors**



#### **Dimensions**



#### %Packaging Code



#### **Dimensions and Packaging Quantities**

Size	Co		Dimension	Dimensions (mm)				Maximum qua			
Size	JIS	EIA	Code	L	W	Т	P min.	P max.	P to P min.	<b>φ180 Reel</b> <sup>®</sup> 40kp (E4/1)	φ330 Reel <sup>®</sup>
02	0402	01005	Α	0.4±0.02	0.2±0.02	0.2±0.02	0.07	0.14	0.13	20kp (P8/2)	80kp (P8/2)
			Α			0.22 max.				30kp (P8/1)	150kp (P8/1)
				0.6±0.03	0.3±0.03		0.10	0.20	0.20	15kp (P8/2) 30kp (P8/1)	50kp (P8/2) 150kp (P8/1)
			В			0.3±0.03				15kp (P8/2)	50kp (P8/2)
03	0603	0201	С	0.6±0.05	0.3±0.05	0.3±0.05	0.13	0.23	0.19	30kp (P8/1)	150kp (P8/1)
			D			0.3±0.09				15kp (P8/2) 15kp (P8/2)	50kp (P8/2) -
			Е	0.6±0.09	0.3±0.09	0.25 max.	0.13	0.23	0.19	15kp (P8/2)	-
			F	0.6±0.10	0.3±0.10	0.3±0.10				15kp (P8/2) 20kp (P8/1)	- 100kp (P8/1)
			Α			0.22 max.				10kp (P8/2)	50kp (P8/2)
			В			0.25 max.				20kp (P8/1) 10kp (P8/2)	100kp (P8/1) 50kp (P8/2)
				4 0 10 05	0.510.05	0.00				20kp (P8/1)	100kp (P8/1)
			С	1.0±0.05	0.5±0.05	0.33 max.				10kp (P8/2)	50kp (P8/2)
			D			0.35 max.				20kp (P8/1) 10kp (P8/2)	100kp (P8/1) 50kp (P8/2)
			Е			0.5±0.05				20kp (P8/1)	100kp (P8/1)
05	1005	0402					0.15	0.35	0.30	10kp (P8/2) 20kp (P8/1)	50kp (P8/2)
			F	1.0±0.07	0.5±0.07	0.5±0.07				10kp (P8/2)	50kp (P8/2)
			G			0.35 max.				20kp (P8/1) 10kp (P8/2)	100kp (P8/1) 50kp (P8/2)
			н	1.0±0.10	0.5±0.10	0.5±0.10				20kp (P8/1)	50kp (P8/2)
										10kp (P8/2) 20kp (P8/1)	,
			J	1.0±0.15	0.5±0.15	0.5±0.15				10kp (P8/2)	50kp (P8/2)
			K	1.0±0.20	0.5±0.20	0.33 max.				10kp (P8/2)	-
			L A			0.5±0.20 0.55 max.				10kp (P8/2) 4kp (P8/4)	- 10kp (P8/4)
			В	1.6±0.10	0.8±0.10	0.8±0.10				8kp (P8/2)	20kp (P8/2)
										4kp (P8/4) 8kp (P8/2)	10kp (P8/4) 20kp (P8/2)
105	1608	0603	С	1.6±0.15	0.8±0.15	0.55 max.	0.20	0.60	0.50	4kp (P8/4)	10kp (P8/4)
			D			0.8±0.15	00			8kp (P8/2) 4kp (P8/4)	20kp (P8/2) 10kp (P8/4)
			E			0.55 max.				8kp (P8/2)	20kp (P8/2)
			F	1.6±0.20	0.8±0.20	0.8±0.20				4kp (P8/4)	10kp (P8/4)
			Α	A 0.55 max.			4kp (P8/4)	10kp (P8/4)			
			B C			0.95 max. 1.00 max.				4kp (P8/4) 4kp (E8/4)	10kp (P8/4) 10kp (E8/4)
			D	2.0±0.10	1.25±0.10	0.6±0.1				4kp (P8/4)	10kp (P8/4)
			E F			0.85±0.10 1.05±0.10				4kp (P8/4) 3kp (E8/4)	10kp (P8/4) 10kp (E8/4)
21	2012	0805	G			1.25±0.10	0.20	0.75	0.70	3kp (E8/4)	10kp (E8/4)
			Н	0.010.45	1.0510.15	0.55 max.				4kp (P8/4)	10kp (P8/4)
			J K	2.0±0.15	1.25±0.15	0.95 max. 1.25±0.15				4kp (P8/4) 3kp (E8/4)	10kp (P8/4) 10kp (E8/4)
			L	2.0±0.20	1.25±0.20	0.95 max.				4kp (P8/4)	10kp (P8/4)
			M A			1.25±0.20 0.95 max.				3kp (E8/4) 4kp (P8/4)	10kp (E8/4) 10kp (P8/4)
			В			1.00 max.				4kp (E8/4)	10kp (E8/4)
			C D	3.2±0.20	1.6±0.15	1.15±0.10 1.25±0.10				3kp (E8/4) 3kp (E8/4)	10kp (E8/4) 10kp (E8/4)
316	3216	1206	E			1.6±0.15	0.30	0.85	1.40	2.5kp (E8/4)	5kp (E8/4)
			F G	3.2±0.20	1.6±0.20	0.95 max. 1.00 max.				4kp (P8/4) 4kp (E8/4)	10kp (P8/4) 10kp (E8/4)
			Н			1.6±0.20				2.5kp (E8/4)	5kp (E8/4)
			J	3.2±0.30	1.6±0.30	1.6±0.30	0.30	0.85	1.90	2kp (E8/4)	- 10kp (E8/4)
			B			1.00 max. 1.40 max.				4kp (E8/4) 3kp (E8/4)	10kp (E8/4)
00	0005	1010	C	0.040.00	0.5+0.00	1.60 max.	0.00	1.00	1.40	2.5kp (E8/4)	5kp (E8/4) 5kp (E8/4)
32	3225	1210	D E	3.2±0.30	2.5±0.20	1.6±0.15 2.20 max.	0.30	1.00	1.40	2.5kp (E8/4) 2kp (E8/4)	5kp (E8/4) 5kp (E8/4)
			F			2.0±0.2				2kp (E8/4)	5kp (E8/4)
	4500	1000	G A	4.510.00	0.010.00	2.5±0.2 1.6 max.	0.15	0.05	0.00	1kp (E8/4) 2kp (E12/4)	4kp (E8/4) -
42	4520	1808	В	4.5±0.20	2.0±0.20	2.2 max.	0.15	0.85	2.60	2kp (E12/4)	-
			A B			2.0 max. 2.0±0.2				1kp (E12/8) 1kp (E12/8)	-
43	4532	1812	С	4.5±0.30	3.2±0.20	2.5 max.	0.30	1.10	10 2.00	0.5kp (E12/8)	-
			D E			2.5±0.2 2.8±0.2				0.5kp (E12/8) 0.5kp (E12/8)	-
52	5720	2208	Α	5.7±0.40	2.0±0.20	2.2 max.	0.15	0.85	4.20	2kp (E12/4)	-
FF	5750	2220	A B	5 7±0 40	5.0+0.40	2.0 max. 2.5 max.	0.20	1 40	2.50	1kp (E12/8)	-
55	5/50	2220	C	5.7±0.40	5.0±0.40	2.5 max. 2.8 max.	0.30	1.40	2.50	0.5kp (E12/8) 0.5kp (E12/8)	-
				•							

Note: Taping denotes the quantity packaged per reel (kp means 1000 pieces). 
\* Please contact us.

# **Multilayer Ceramic Chip Capacitors Ordering Information**



KYOCERA PART NUM	MBER	<u>CM</u>	<u>03</u>	X5R	<u>225</u>	<u>M</u>	06	<u>A</u>	<u> </u>
SERIES CODE									
CM = General Purpose CT = Low Profile CU = High-Q	AT = Au terminatio ST = Soft terminat CF = High Voltage	tion							
SIZE CODE —									
<b>SIZE EIA (JIS)</b> 02 = 01005 (0402)	SIZE EIA (JIS) 32 = 1210 (3225) 42 = 1808 (4520) 43 = 1812 (4532) 52 = 2208 (5720) 55 = 2220 (5750)								
DIELECTRIC CODE -									
CODE EIA CODE CG = C0G (NPO) X5R = X5R X7R = X7R Negative temperature coeffici	X7S = X7S X6S = X6S (Option) ent dielectric types are avail	lable on request.							
CAPACITANCE CODE									
Capacitance expressed in pF. Two significant digits plus nur For Values < 10pF, Letter R de eg. 100000pF = 104 0.1µF = 104 4700pF = 472	nber of zeros.								
<b>TOLERANCE CODE</b>									
$B = \pm 0.1 pF$ G	= $\pm 0.5$ pF								
VOLTAGE CODE —									
06 = 6.3 Vdc 250	= 250Vdc 2000 = = 630Vdc 3000 =	= 1000Vdc = 2000Vdc = 3000Vdc = 4000Vdc							
TERMINATION CODE									
A = Nickel Barrier/ Tin			r/ Cu	S =	Nickel (Soft Te				
PACKAGING CODE -									
T = 7" Reel Taping & 4mm Q = 7" Reel Taping & 1mm L = 13" Reel Taping & 4mm	Cavity pitch	H = 7" Reel Tapin N = 13" Reel Tapin W = 13" Reel Tapin *P = 7" Reel Tapin * Carrier tape width 4 *1 Applied to size 43 t	ng & 2m ng & 1m ng & 1m 4mm.	nm Cavit nm Cavit	y pitch y pitch				
OPTION —		,,	-						

Above digits are used to track individual specification except for CT Series. Maximum thickness is indicated in CT Series.

EX. 125  $\rightarrow$  1.25mm max. 095  $\rightarrow$  0.95mm max.

## **Multilayer Ceramic Chip Capacitors Temperature Characteristics and Tolerance**



#### **Temperature Compensation Type**

Code	ppm	ı/ °C	Temperature Range
CG	0	±30	−55 to 125°C
CH	U	±60	-55 10 125 0

Note: All parts of COG will be marked as "CG" but will conform to the above table.

#### **High Dielectric Constant Type**

EIA Dielectric	Temperature Range	∆C max.	
X5R	−55 to 85°C	±15%	
X7R	−55 to 125°C	11370	
X7S	−55 to 125°C	±22%	
*X6S	−55 to 105°C	1 122%	

<sup>\*</sup> option

#### **Available Tolerances**

Dielectric materials, capacitance values and tolerances are available in the following combinations only:

EIA Dielectric	Tolerance	Capacitance
	*2 A = ±0.05pF	<0.5pF
	B = ±0.1pF	≤5pF
	C = ±0.25pF	*1 <10pF
COG	$D = \pm 0.50 pF$	< TOPF
	*2 G = ±2%	
	J = ±5%	≥10pF E12 Series
	$K = \pm 10\%$	E12 Series
*.	$^{*_2} J = \pm 5\%$	
*2 X6S X5R X7S X7R	$K = \pm 10\%$	*3 E3 Series
7C 7	$M = \pm 20\%$	

#### Note:

#### **E Standard Number**

<b>E</b> 3	<b>E</b> 6	E12	E24 (Option)		
	1.0	1.0	1.0	1.1	
1.0	1.0	1.2	1.2	1.3	
1.0	1.5	1.5	1.5	1.6	
	1.5	1.8	1.8	2.0	
	2.2	2.2	2.2	2.4	
2.2	2.2	2.7	2.7	3.0	
2.2	3.3	3.3	3.3	3.6	
		3.9	3.9	4.3	
	4.7	4.7	4.7	5.1	
4.7	4.7	5.6	5.6	6.2	
4.7	6.8	6.8	6.8	7.5	
	0.0	8.2	8.2	9.1	

Temperature coefficients are determined by calculation based on measurement at 20°C and 85°C.

<sup>\*1</sup> Nominal values below 10pF are available in the standard values of 0.5pF, 1.0pF, 1.5pF, 2.0pF, 3.0pF, 4.0pF, 5.0pF, 6.0pF, 7.0pF, 8.0pF, 9.0pF

<sup>\*2</sup> option

<sup>\*3</sup> E6 series is available on request.

### **CM Series** General



### [RoHS Compliant Products]

#### **Features**

We offer a diverse product line ranging from ultra-compact (0.4×0.2mm) to large (4.5×3.2mm) components configured for a variety of temperature characteristics, rated voltages, and packages. We offer the choice and flexibility for almost any applications.

#### **Applications**

This standard type is ideal for use in a wide range of applications, from commercial to industrial equipment.

#### **Temperature Compensation Dielectric**

(EIA	ze Code)	(01	ЛО2 005)	(02	M03 201)	CM05 (0402)	CM105 (0603)		CM21 (0805)		
	erature	C	∆*1	C.	∆*1	<b>C</b> ∆*1	<b>C</b> ∆*1	<b>C</b> ∆*1			
	Itage (Vdc)	16	25	5 25 50		50	50	16 25		50	
Capacit	ance (pF)										
R20 R50 1R0 1R5	0.2 0.5 1.0 1.5 2.0 3.0 4.0 5.0 6.0										
	3.0 4.0 5.0										
	7.0 8.0 9.0 10		Α								
100 120	10	Α		В							
120	15				В						
	18 22 27 33 39 47 56 68 82 100										
	47 56										
101 121	82 100										
121	150 150 180 220										
	270 270 330 390					E					
	390 470 560 680 820										
102	820 1000						В				
102 122	1000 1200 1500 1800									E	
	2200 2700 3300								E G		
	3900 4700 5600								G		
103 123	6800 8200 10000							G			
123	12000 15000 18000										

<sup>&</sup>lt;Standard Capacitance Value>

E12 Series

Please contact for capacitance value other than standard.

Alphabets in capacitance chart denote dimensions. Please refer to the below table for detail.

(Example) In case of "B" for CM03; L: 0.6±0.03mm W: 0.3±0.03mm

T: 0.3±0.03mm

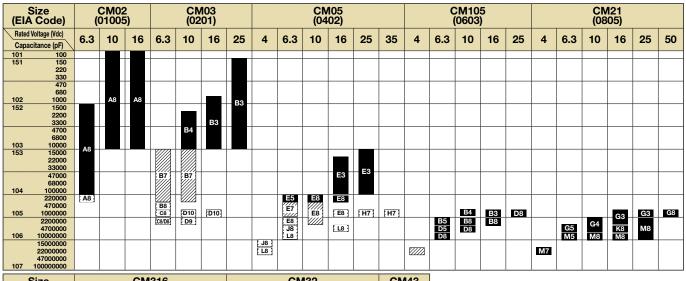
Size	Size	Dimension (mm)						
Size	Code	L	w	Т				
02	A	0.4±0.02	0.2±0.02	0.2±0.02				
03	В	0.6±0.03	0.3±0.03	0.3±0.03				
05	E	1.0±0.05	0.5±0.05	0.5±0.05				
105	В	1.6±0.10	0.8±0.10	0.8±0.10				
21	Е	2.0±0.10	1.25±0.10	0.85±0.10				
21	G	2.0±0.10	1.25±0.10	1.25±0.10				

<sup>\*1:</sup> CG,CH



### [RoHS Compliant Products]

#### **X5R Dielectric**



	Size A Code)	CM316 (1206)					CM32 (1210)					CN (18			
	d Voltage (Vdc)	6.3	10	16	25	50	100	4	6.3	10	16	25	50	6.3	50
105	220000 470000 1000000						H3					В3	F1		
106	2200000 4700000 10000000	<b>E</b> 5	E4	E3	E3 H8	[H3]				F4	C3	F3 G3 G8	G3		D1
107	22000000 47000000 100000000	Н5	Н8	Н8				G5	G5	G4	G3	G8		<b>E</b> 5	

<Standard Capacitance Value>

CM21 size and smaller : E6 Series

CM316 size and larger / capacitance value of  $0.1 \mu F$  and larger : E3 Series

Please contact for capacitance value other than standard.

Optional Spec.

Two digits alphanumerics in capacitance chart denote dimensions and tan  $\delta.$  Please refer to the below table for detail.

#### (Example)

In case of "B3" for CM03;

L :  $0.6\pm0.03$ mm W :  $0.3\pm0.03$ mm T :  $0.3\pm0.03$ mm Tan  $\delta$  : 5.0% max.

Size	Size	Dir	nension (m	ım)	
Size	Code	L	w	Т	
02	Α	0.4±0.02	0.2±0.02	0.2±0.02	
	В	0.6±0.03	0.3±0.03	0.3±0.03	
03	С	0.6±0.05	0.3±0.05	0.3±0.05	
	D	0.6±0.09	0.3±0.09	0.3±0.09	
	E	1.0±0.05	0.5±0.05	0.5±0.05	
05	Н	1.0±0.10	0.5±0.10	0.5±0.10	
03	J	1.0±0.15	0.5±0.15	0.5±0.15	
	L	1.0±0.20	0.5±0.20	0.5±0.20	
105	В	1.6±0.10	0.8±0.10	0.8±0.10	
105	D	1.6±0.15	0.8±0.15	0.8±0.15	
	G	2.0±0.10	1.25±0.10	1.25±0.10	
21	K	2.0±0.15	1.25±0.15	1.25±0.15	
	М	2.0±0.20	1.25±0.20	1.25±0.20	

Size	Size	Dir	Dimension (mm)							
Size	Code	L	W	Т						
316	E	3.2±0.20	1.6±0.15	1.6±0.15						
310	Н	3.2±0.20	1.6±0.20	1.6±0.20						
	В	3.2±0.30	2.5±0.20	1.40 max.						
32	С	3.2±0.30	2.5±0.20	1.60 max.						
32	F	3.2±0.30	2.5±0.20	2.0±0.2						
	G	3.2±0.30	2.5±0.20	2.5±0.2						
43	D	4.5±0.30	3.2±0.20	2.5±0.2						
43	E	4.5±0.30	3.2±0.20	2.8±0.2						

Tan $\delta$ Code	Tan δ
1	2.5% max.
3	5.0% max.
4	7.0% max.
5	7.5% max.
7	10.0% max.
8	12.5% max.
9	15.0% max.
10	20.0% max.



### [RoHS Compliant Products]

#### **X7R Dielectric**

	Size A Code)	CM02 (01005)		CM03 (0201)		CN (04	105 ·02)		CM105 (0603)				CM21 (0805)		
	Voltage (Vdc)	16	10	16	25	16	25	6.3	10	16	6.3	10	16	25	50
101 151	100 150 220 330			B2	B2										
102 152	470 680 1000 1500	A8		62											
.02	2200 3300 4700 6800		В3 —												
103 153	10000 15000 22000					E2	E3								
104	33000 47000 68000 100000					E8	E8								
105	220000 470000 1000000 2200000							D8	B8	B8		G3	G8	G8 M8	[M3]
106	4700000 10000000 22000000							D6			M8	M8 [M8]	M8	IVIS	

Size (EIA Code)		CM316 (1206)				CM32 (1210)			CM43 (1812)		
Rated Voltage (Vdc) Capacitance (pF)	6.3	10	16	25	50	10	16	25	50	50	100
220000 470000 105 1000000			C2	E2				B2	FI	B1	D1
2200000 4700000 106 10000000 22000000	H8	E3 H8	Н8	H8 (H3)	[H3]	G8	G2 G8	F2 G8	G3	D1	

Optional Spec.

<Standard Capacitance Value>

CM21 size and smaller : E6 Series

CM316 size and larger / capacitance value of  $0.1\mu\text{F}$  and larger : E3 Series

Please contact for capacitance value other than standard.

Two digits alphanumerics in capacitance chart denote dimensions and tan  $\delta.$  Please refer to the below table for detail.

#### (Example)

In case of "B3" for CM03;

L : 0.6±0.03mm W: 0.3±0.03mm T : 0.3±0.03mm Tan δ: 5.0% max.

Size	Size Code	Dir	Dimension (mm)			
Size	Code	L	W	Т		
02	Α	0.4±0.02	0.2±0.02	0.2±0.02		
03	В	0.6±0.03	0.3±0.03	0.3±0.03		
05	E	1.0±0.05	0.5±0.05	0.5±0.05		
105	В	1.6±0.10	0.8±0.10	0.8±0.10		
105	D	1.6±0.15	0.8±0.15	0.8±0.15		
21	G	2.0±0.10	1.25±0.10	1.25±0.10		
21	М	2.0±0.20	1.25±0.20	1.25±0.20		

Size	Size	Dimension (mm)				
Size	Code	L	w	Т		
	С	3.2±0.20	1.6±0.15	1.15±0.10		
316	E	3.2±0.20	1.6±0.15	1.6±0.15		
	Н	3.2±0.20	1.6±0.20	1.6±0.20		
	В	3.2±0.30	2.5±0.20	1.40 max.		
32	F	3.2±0.30	2.5±0.20	2.0±0.2		
	G	3.2±0.30	2.5±0.20	2.5±0.2		
43	В	4.5±0.30	3.2±0.20	2.0±0.2		
43	D	4.5±0.30	3.2±0.20	2.5±0.2		

$\begin{array}{c} \text{Tan } \delta \\ \text{Code} \end{array}$	Tan δ
1	2.5% max.
2	3.5% max.
3	5.0% max.
5	7.5% max.
8	12.5% max.

#### **X7S Dielectric**

Size (EIA Code)	CM316 (1206)
Rated Voltage (Vdc) Capacitance (pF)	100
47000 104 100000	
220000 470000 105 1000000	
2200000 4700000 106 10000000 22000000	∑ J3 ∑

Size	Size	Size Dimension (mm)				
Size	Size Code	L	W	Т		
316	Н	3.2±0.20	1.6±0.20	1.6±0.20		
310	J	3.2±0.30	1.6±0.30	1.6±0.30		

$\begin{array}{c} \text{Tan } \delta \\ \text{Code} \end{array}$	Tan a
3	5.0% max.

Two digits alphanumerics in capacitance chart denote dimensions and tan  $\delta.$  Please refer to the above table for detail.



## **Multilayer Ceramic Chip Capacitors Test Conditions and Standards**



## Test Conditions and Specifications for Temperature Compensation Type (C△ Characteristics) CM/ CU/ CF Series

Test Items			Test Condition	ns	Specifications	
Capacitance V	/alue (C)	Capacitan	ce Frequency	Volt	Within tolerance	
Q		C≤1000pl C>1000pl	F 1MHz±10%	0.5 to 5Vrms	C≥30pF: Q≥1000 C<30pF: Q≥400+20C	
Insulation Resistance (IR)		Measured after the rated voltage is applied for 1 minute at room ambient.  For the rated voltage of over 630V, apply 500V for 1 minute at room ambient.  The charge and discharge current of the capacitor must not exceed 50mA.			Over 10000M $\Omega$ or 500M $\Omega$ • $\mu$ F, whichever is less	
Dielectric Res	istance	Apply 3 times of the rated voltage for 1 to 5 seconds. Apply 1.5 times when the rated voltage is 250V or over. Apply 1.2 times when the rated voltage is 630V or over. The charge and discharge current of the capacitor must not exceed 50mA.			No problem observed	
Appearance		Microscope			No problem observed	
Termination S	trength		rard force of 500g ple. Apply 2N for 0		No problem observed	
Bending Stren	gth	Glass epoxy P time 10 second	CB: Fulcrum spacir ds.	ng: 90mm, duration	No significant damage at 1mm bent	
Vibration	Appearance		uency: 10 to 55 (H	z)	No problem observed	
Test	ΔC	Amplitude: 1.5 Sweeping cor	5mm idition: 10→55→10	)Hz/ 1 minute in X,	Within Tolerance	
	Q	Y and Z	nours each, 6 hour		C≥30pF : Q≥1000 C<30pF : Q≥400+20C	
Soldering	Appearance	Soak the sample in 260°C±5°C solder for 10±0.5			No problem observed	
Heat Resistance	ΔC	seconds and after 24±2 hou	place in room amb urs	ient, and measure	Within ±2.5% or ±0.25pF, whichever is larger	
	Q	(Pre-heating conditions)			C≥30pF: Q≥1000	
		Order	Temperature	Time	C<30pF: Q≥400+20C	
	IR	2	80 to 100°C 150 to 200°C	2 minutes 2 minutes	Over $10000 M\Omega$ or $500 M\Omega$ • $\mu F$ whichever is less	
	Withstanding Voltage	The charge ar	nd discharge curre eed 50mA for IR ar	nt of the capacitor	Resist without problem	
Solderablity		Soaking condition           Sn-3Ag-0.5Cu         245±5°C         3±0.5 sec.           Sn63 Solder         235±5°C         2±0.5 sec.			Solder coverage : 90% min.	
Temperature	Appearance	(Cycle)			No problem observed	
Cycle	ΔC	Room temper	ature (3min.)→		Within ±2.5% or ±0.25pF, whichever is larger	
	Q	Lowest opera	tion temperature (3 ature (3min.)→	30min.)→	C≥30pF: Q≥1000 C<30pF: Q≥400+20C	
	IR	Highest opera	tion temperature(3	30min.)	Over 10000M $\Omega$ or 500M $\Omega$ • $\mu$ F, whichever is less	
	Withstanding Voltage	The charge ar	, measure after 24: nd discharge currel red 50mA for IR ar urement.	nt of the capacitor	Resist without problem	
Load	Appearance	After applying	rated voltage for	500+12/ –0 hours	No problem observed	
Humidity Test	ΔC		on at 40°C±2°C, hu parts to stabilize	•	Within ±7.5% or ±0.75pF, whichever is larger	
(Except CF Series)	Q	room tempera	r parts to stabilize ature before measu nd discharge currel	irement.	C≥30pF : Q≥200	
IR		-	eed 50mA for IR m		Over 500M $\Omega$ or 25M $\Omega$ • $\mu$ F, whichever is less	
High-	Appearance	After applying	twice the rated vo	oltage at the	No problem observed.	
Temperature with Loading	ΔC	temperature o	of 125±3°C for 100	0+12/ -0 hours,	Within ±3% or ±0.3pF, whichever is larger	
With Loading	Q	Apply 1.5 times Apply 1.2 times	cample after 24±2 In when the rated volt is when the rated volt in discharge current	age is 250V or over. age is 630V or over.	C≥30pF: Q≥350 10pF <c<30pf: 2<br="" q≥275+5c="">C&lt;10pF: Q≥200+10C</c<30pf:>	
	IR	must not exce	eed 50mA for IR m	easurement.	Over $1000M\Omega$ or $50M\Omega$ • $\mu\text{F}$ , whichever is less	

Please ask for individual specification for the hatched range in previous chart.

## **Multilayer Ceramic Chip Capacitors Test Conditions and Standards**



## Test Conditions and Specifications for High Dielectric Type (X5R, X7R) CM/ CT Series

Test Items		Test Conditions	Specifications
Capacitance Value (C)		Measure after heat treatment	Within tolerance
Tanδ (%)		Capacitance         Frequency         Volt           C≤10μF         1kHz±10%         1.0±0.2Vrms           C>10μF         120Hz±10%         0.5±0.2Vrms	Refer to capacitance chart
Insulation Res	sistance (IR)	Measured after the rated voltage is applied for 1 minute at room ambient. The charge and discharge current of the capacitor must not exceed 50mA.	Over 10000M $\Omega$ or 500M $\Omega$ • $\mu$ F, whichever is less
Dielectric Res	istance	Apply 2.5 times of the rated voltage for 1 to 5 seconds. The charge and discharge current of the capacitor must not exceed 50mA.	No problem observed
Appearance		Microscope	No problem observed
Termination S	trength	Apply a sideward force of 500g (5N) to a PCB-mounted sample. note: 2N for 0201 size, and 1N for 01005 size. Exclude CT series with thickness of less than 0.66mm.	No problem observed
Bending Stren	gth	Glass epoxy PCB: Fulcrum spacing: 90mm, duration time 10 seconds. Exclude CT series with thickness of less than 0.66mm.	No significant damage at 1mm bent
Vibration	Appearance	Take the initial value after heat treatment.	No problem observed
Test	ΔC	Vibration frequency: 10 to 55 (Hz) Amplitude: 1.5mm	Within tolerance
	Tanδ (%)	Sweeping condition: 10→55→10Hz/ 1 minute in X, Y and Z Directions: 2 hours each, 6 hours total.	Within tolerance
Soldering	Appearance	Take the initial value after heat treatment.	No problem observed
Heat Resistance	ΔC	Soak the sample in 260°C±5°C solder for 10±0.5 seconds and place in room ambient, and measure	Within ±7.5%
nesistance	Tanδ (%)	after 24±2 hours.	Within tolerance
	IR	(Pre-heating conditions)	Over 10000M $\Omega$ or 500M $\Omega$ • $\mu$ F, whichever is less
	Withstanding Voltage	Order         Temperature         Time           1         80 to 100°C         2 minutes           2         150 to 200°C         2 minutes   The charge and discharge current of the capacitor must not	Resist without problem
Solderablity		exceed 50mA for IR and withstanding voltage measurement.  Soaking condition  Sn-3Ag-0.5Cu 245±5°C 3±0.5 sec. Sn63 Solder 235±5°C 2±0.5 sec.	Solder coverage : 90% min.
Temperature Cycle	Appearance	Take the initial value after heat treatment. (Cycle)	No problem observed
Cycle	ΔC	Room temperature (3min.)→	Within ±7.5%
	Tanδ (%)	Lowest operation temperature (30min.)→	Within tolerance
	IR	Room temperature (3min.)→ Highest operation temperature(30min.)	Over 10000M $\Omega$ or 500M $\Omega$ • $\mu$ F, whichever is less
	Withstanding Voltage	After 5 cycles, measure after 24±2 hours. The charge and discharge current of the capacitor must not exceed 50mA for IR and withstanding voltage measurement.	Resist without problem
Load	Appearance	Take the initial value after voltage treatment.	No problem observed
Humidity Test	ΔC	After applying rated voltage for 500+12/ –0 hours in pre-condition at 40°C±2°C, humidity 90 to	Within ±12.5%
iest	Tanδ (%)	95%RH, allow parts to stabilize for 24±2 hours, at	200% max. of initial value
	IR	room temperature before measurement. The charge and discharge current of the capacitor must not exceed 50mA for IR measurement.	Over $500 \text{M}\Omega$ or $25 \text{M}\Omega$ • $\mu\text{F}$ , whichever is less
High-	Appearance	Take the initial value after voltage treatment.	No problem observed
Temperature	ΔC	After applying twice the rated voltage at the highest operation temperature for 1000+12/ –0 hours,	Within ±12.5%
with Loading	Tanδ (%)	measure the sample after 24±2 hours.	200% max. of initial value
Loading	IR	The charge and discharge current of the capacitor must not exceed 50mA for IR measurement.  Apply 1.5 times when the rated voltage is 10V or less. Applied voltages for respective products are indicated in the below chart.	Over 1000M $\Omega$ or 50M $\Omega$ • $\mu$ F, whichever is less

Pre-treat-	Heat	Keep specimen at 150+0/ –10°C for 1 hour, leave specimen at room ambient for 24±2 hours.
ment	Voltage	Apply the same test condition for 1 hour, then leave the specimen at room ambient for 24±2 hours.

High-temperature with Loading Applied Voltage (Rated Voltage × □ )

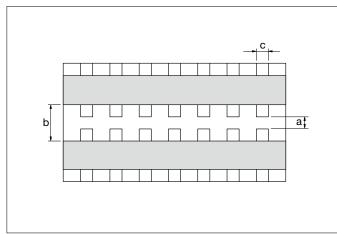
Applied Voltage	Rated Voltage	Products			
	4V	CT03X5R104			
×1.3	6.3V	CM105X5R475, CM316X5R476, CM02X5R153·104			
	0.30	CT05X5R104, CT21X5R106, CT03X5R104			
	16V	CM02X7R101-222, CM05X7R333-104, CM105X7R105, CM21X7R105-475, CM316X7R475-106, CM32X7R106-226, CM05X5R224, CM105X5R225, CM21X5R475-106, CM316X5R226			
	160	CT105X5R105, CT21X5R225-475, CT316X5R106, CM03X5R332-103, CM02X5R101-103			
	25V	CM21X7R105-225, CM316X7R475, CM32X7R106, CM105X5R105, CM21X5R225-106, CM316X5R106, CM32X5R106-226			
×1.5	250	CT316X5R225-106, CM03X5R152-103, CM05X7R103-104			
	50V	CM21X5R105, CM32X5R106, CM32X7R106			
	300	CT21X5R225, CT316X5R105-475			
	100V	CM43X7R105			

### Multilayer Ceramic Chip Capacitors Test Conditions and Standards



(Unit: mm)

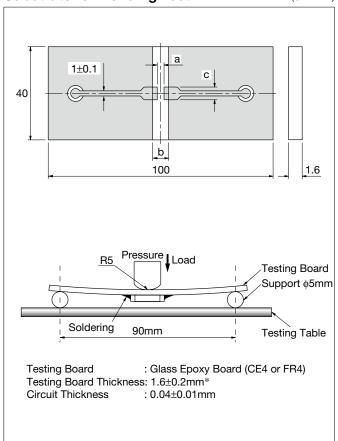
#### **Substrate for Electrical Tests**



Size (EIA Code)	а	b	С
02 (01005)	0.15	0.50	0.20
03 (0201)	0.26	0.92	0.32
05 (0402)	0.4	1.4	0.5
105 (0603)	1.0	3.0	1.2
21 (0805)	1.2	4.0	1.65
316 (1206)	2.2	5.0	2.0
32 (1210)	2.2	5.0	2.9
42 (1808)	3.5	7.0	3.7
43 (1812)	3.5	7.0	3.7
52 (2208)	4.5	8.0	5.6
55 (2220)	4.5	8.0	5.6

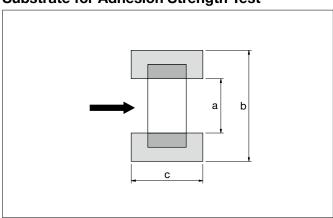
#### **Substrate for Bending Test**





#### \* 02, 03, 05 size 0.8±0.1mm

#### **Substrate for Adhesion Strength Test**

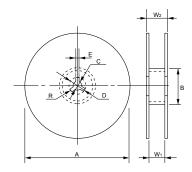


## **Multilayer Ceramic Chip Capacitors Packaging Options**



#### **Tape and Reel**

• Reel



#### Reel

(Unit: mm)

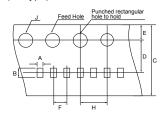
Code Reel	A	В	С	D	
7-inch Reel (CODE: T, H, Q)	180 +0 -2.0				
7-inch Reel (CODE: P)	178±2.0	ф60 min.	13±0.5	21±0.8	
13-inch Reel (CODE: L, N, W)	330±2.0				
Code Reel	E	<b>W</b> 1	<b>W</b> 2	R	
	E	<b>W</b> <sub>1</sub>	<b>W</b> <sub>2</sub> 16.5 max.	R	
Reel 7-inch Reel	<b>E</b> 2.0±0.5			1.0	

<sup>\*</sup> Carrier tape width 8mm.

For size 42 (1808) or over, Tape width 12mm and W1:  $14\pm1.5$ , W2: 18.4mm max.

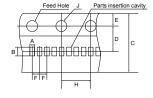
### **Carrier Tape**

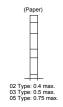
F = 1mm (02 Type)



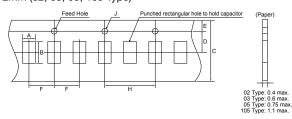


F = 1mm (02, 03, 05 Type)

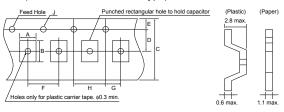




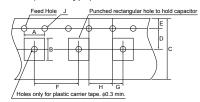
F = 2mm (02, 03, 05, 105 Type)

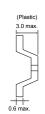


#### F = 4mm (105, 21, 316, 32, 42, 52 Type)



#### F = 8mm (43, 55 Type)





#### Carrier Tape (Unit: mm)

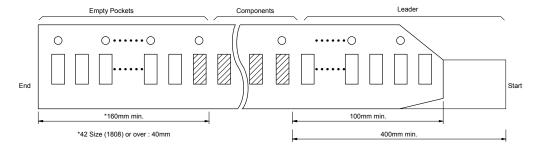
Outrice rap	Cont. min									
Size (EIA Code)	Α	В	С	D	E	F	G	н	J	Carrier Tape
00 (01005)*	0.23±0.02	0.43±0.02	4.0±0.08	1.8±0.02	0.9±0.05	1.0±0.02	_	2.0±0.04	0.8±0.04	4mm, Plastic
02 (01005)*	0.25±0.03	0.45±0.03	8.0±0.3	3.5±0.05	1.75±0.1	2.0±0.05	_	4.0±0.1	1.5+0.1/-0	8mm, Paper
03 (0201)*	0.37±0.03	0.67±0.03	8.0+0.3/-0.1	3.5±0.05	1.75±0.1	1.0±0.05	_	4.0±0.05	1.5+0.1/-0	8mm, Paper
03 (0201)	0.37±0.03	0.67±0.03	8.0±0.3	3.5±0.05	1.75±0.1	2.0±0.05	_	4.0±0.1	1.5+0.1/-0	8mm, Paper
05 (0402)*	0.65±0.1	1.15±0.1	8.0+0.3/-0.1	3.5±0.05	1.75±0.1	1.0±0.05	_	4.0±0.05	1.5+0.1/-0	8mm, Paper
05 (0402)	0.65±0.1	1.15±0.1	8.0±0.3	3.5±0.05	1.75±0.1	2.0±0.05	_	4.0±0.1	1.5+0.1/-0	8mm, Paper
105 (0603)	1.0±0.2	1.8±0.2	8.0±0.3	3.5±0.05	1.75±0.1	4.0±0.1	2.0±0.05	4.0±0.1	1.5+0.1/-0	8mm, Paper
21 (0805)	1.5±0.2	2.3±0.2	8.0±0.3	3.5±0.05	1.75±0.1	4.0±0.1	2.0±0.05	4.0±0.1	1.5+0.1/-0	8mm, Paper
21 (0003)	1.5±0.2	2.3±0.2	8.0±0.3	3.5±0.05	1.75±0.1	4.0±0.1	2.0±0.05	4.0±0.1	1.5+0.1/-0	8mm, Plastic
316 (1206)	2.0±0.2	3.6±0.2	8.0±0.3	3.5±0.05	1.75±0.1	4.0±0.1	2.0±0.05	4.0±0.1	1.5+0.1/-0	8mm, Paper
310 (1200)	2.0±0.2	3.6±0.2	8.0±0.3	3.5±0.05	1.75±0.1	4.0±0.1	2.0±0.05	4.0±0.1	1.5+0.1/-0	8mm, Plastic
32 (1210)	2.9±0.2	3.6±0.2	8.0±0.3	3.5±0.05	1.75±0.1	4.0±0.1	2.0±0.05	4.0±0.1	1.5+0.1/-0	8mm, Plastic
42 (1808)	2.4±0.2	4.9±0.2	12.0±0.3	5.5±0.05	1.75±0.1	4.0±0.1	2.0±0.05	4.0±0.1	1.5+0.1/-0	12mm, Plastic
43 (1812)	3.6±0.2	4.9±0.2	12.0±0.3	5.5±0.05	1.75±0.1	8.0±0.1	2.0±0.05	4.0±0.1	1.5+0.1/-0	12mm, Plastic
52 (2208)	2.4±0.2	6.0±0.2	12.0±0.3	5.5±0.05	1.75±0.1	4.0±0.1	2.0±0.05	4.0±0.1	1.5+0.1/-0	12mm, Plastic
55 (2220)	5.3±0.2	6.0±0.2	12.0±0.3	5.5±0.05	1.75±0.1	8.0±0.1	2.0±0.05	4.0±0.1	1.5+0.1/-0	12mm, Plastic

<sup>\*</sup> Option

## **Multilayer Ceramic Chip Capacitors Packaging Options**



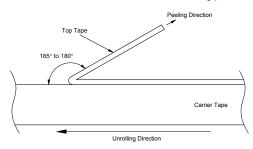
#### **Detail of leader and trailer**



#### Adhesive tape

- 1) The exfoliative strength when peeling off the top tape from the carrier tape by the method of the following figure shall be \*0.1 to 0.7N. \*02 Size: 0.1 to 0.5N
- 2) When the top tape is peeled off, the adhesive stays on the top tape.
- 3) Chip capacitors will be in a state free without being stuck on the thermal adhesive tape.

Exfoliating angle: 165 to 180 degrees to the carrier tape. Exfoliating speed: 300 mm/min.



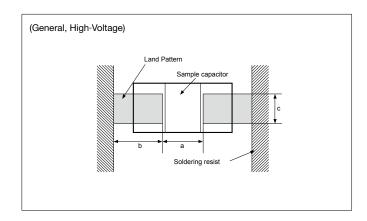
## Multilayer Ceramic Chip Capacitors Surface Mounting Information



#### Dimensions for recommended typical land

Since the amount of solder (size of fillet) to be used has direct influence on the capacitor after mounting, the sufficient consideration is necessary.

When the amounts of solder is too much, the stress that a capacitor receives becomes larger. It may become the cause of a crack in the capacitor. When the land design of printed wiring board is considered, it is necessary to set up the form and size of land pattern so that the amount of solder is suitable.



#### General, High-Voltage

(Unit: mm)

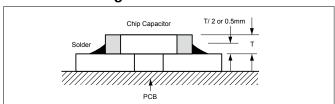
Size (EIA Code)	L×W	а	b	С
02 (01005)	0.4×0.2	0.13 to 0.20	0.12 to 0.18	0.20 to 0.23
03 (0201)	0.6×0.3	0.20 to 0.30	0.25 to 0.35	0.30 to 0.40
05 (0402)	1.0×0.5	0.30 to 0.50	0.35 to 0.45	0.40 to 0.60
105 (0603)	1.6×0.8	0.70 to 1.00	0.80 to 1.00	0.60 to 0.80
21 (0805)	2.0×1.25	1.00 to 1.30	1.00 to 1.20	0.80 to 1.10
316 (1206)	3.2×1.6	2.10 to 2.50	1.10 to 1.30	1.00 to 1.30
32 (1210)	3.2×2.5	2.10 to 2.50	1.10 to 1.30	1.90 to 2.30
42 (1808)	4.5×2.0	2.50 to 3.20 <sup>*</sup> 1	1.80 to 2.30	1.50 to 1.80
43 (1812)	4.5×3.2	2.50 to 3.20*1	1.80 to 2.30	2.60 to 3.00
52 (2208)	5.7×2.0	4.20 to 4.70	2.00 to 2.50	1.50 to 1.80
55 (2220)	5.7×5.0	4.20 to 4.70	2.00 to 2.50	4.20 to 4.70

 $<sup>^{*}</sup>$ 1 Dimension of 3.0 to 3.5mm is recommended for "a", in the case of High-Voltage products.

#### Design of printed circuit and Soldering

The recommended fillet height shall be 1/2 of the thickness of capacitors or 0.5mm. When mounting two or more capacitors in the common land, it is necessary to separate the land with the solder resist strike so that it may become the exclusive land of each capacitor.

#### **Ideal Solder Height**



Item	Not recommended example	Recommended example/ Separated by solder
Multiple parts mount		Solder resist
Mount with leaded parts	Leaded parts	Solder resist  Leaded parts
Wire soldering after mounting	Soldering iron Wire	Solder resist
Overview	Solder resist	Solder resist

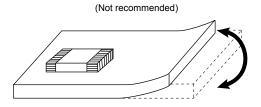
## Multilayer Ceramic Chip Capacitors Surface Mounting Information

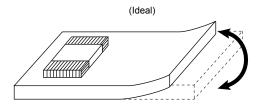


#### **Mounting Design**

The chip could crack if the PCB warps during processing after the chip has been soldered.

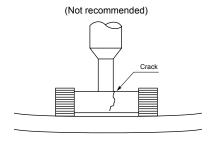
#### Recommended chip position on PCB to minimize stress from PCB warpage

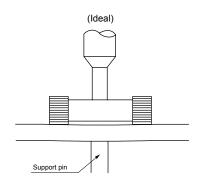




#### **Actual Mounting**

- 1) If the position of the vacuum nozzle is too low, a large force may be applied to the chip capacitor during mounting, resulting in cracking.
- 2) During mounting, set the nozzle pressure to a static load of 1 to 3 N.
- 3) To minimize the shock of the vaccum nozzle, provide a support pin on the back of the PCB to minimize PCB flexture.





4) Bottom position of pick up nozzle should be adjusted to the top surface of a substrate which camber is corrected.

#### **Resin Mold**

- 1) If a large amount of resin is used for molding the chip, cracks may occur due to contraction stress during curing. To avoid such cracks, use a low shrinkage resin.
- 2) The insulation resistance of the chip will degrade due to moisture absorption. Use a low moisture absorption resin.
- 3) Check carefully that the resin does not generate a decomposition gas or reaction gas during the curing process or during normal storage. Such gases may crack the chip capacitor or damage the device itself.

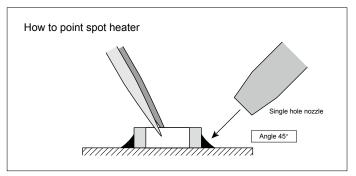
## **Multilayer Ceramic Chip Capacitors Surface Mounting Information**



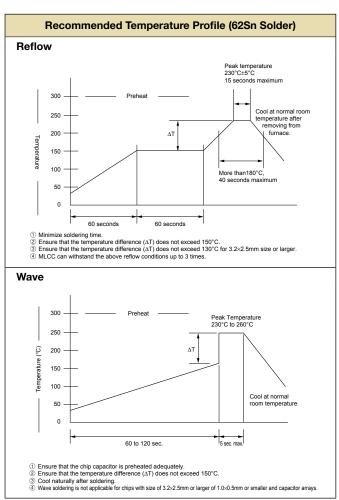
#### **Soldering Method**

- 1) Ceramic is easily damaged by rapid heating or cooling. If some heat shock is unavoidable, preheat enough to limit the temperature difference (Delta T) to within 150 degree Celsius.
- 2) The product size 1.6×0.8mm to 3.2×1.6mm can be used in reflow and wave soldering, and the product size of bigger than 3.2×1.6mm, or smaller than 1.6×0.8mm can be used in reflow.
  - Circuit shortage and smoking can be created by using capacitors which are used neglecting the above caution.
- 3) Please see our recommended soldering conditions.
- 4) In case of using Sn-Zn Solder, please contact us in advance.
- 5) The following condition is recommended for spot heater application.
- · Recommended spot heater condition

Item	Condition		
Distance	5mm min.		
Angle	45°		
Projection Temp.	400°C max.		
Flow rate	Set at the minimum		
Nozzle diameter	2φ to 4φ (Single hole type)		
Application time	10 sec. max. (1206 and smaller) 30 sec.max. (1210 and larger)		



### Recommended Temperature Profile (Sn-3Ag-0.5Cu) Reflow 250°C±5°C 5 to 10 sec. max 300 Preheat 250 Cool at normal 200 170 to 180°C 150 0 90±30 sec. ① Minimize soldering time. ② Ensure that allowable temperature difference does not exceed 150°C. ③ Ensure that allowable temperature difference does not exceed 130°C for 3.2×2.5mm size or larger. Wave Peak Temperatur 245°C to 260°C 250 ္စ 200 ΔΊ 100 0 5 sec. max 60 to 120 sec. ① Ensure that the chip capacitor is preheated adequately. ② Ensure that the temperature difference ( $\Delta T$ ) does not exceed 150°C. Cool naturally after soldering. Wave soldering is not applicable for chips with size of 3.2×2.5mm or larger of 1.0×0.5mm or smaller and capacitor arrays.



#### Soldering iron

1) Temperature of iron chip

1206 and smaller 350°C max.

2) Wattage

3) Tip shape of soldering iron

4) Soldering Time

1210 and larger 280°C max.

80W max.

φ3.0mm max.

3 sec. max.

5) Cautions

a) Pre-heating is necessary rapid heating must be avoided.

Delta T≤150°C (product size of bigger than 3.2×1.6mm. Delta T≤130°C)

- b) Avoid direct touching to capacitors.
- c) Avoid rapid cooling after soldering. Natural cooling is recommended.
- \*Consult as if it is difficult to keep the temperature 280°C max. for 1210 and larger MLCC'S.

## Multilayer Ceramic Chip Capacitors Precautions



#### **Circuit Design**

- 1. Once application and assembly environments have been checked, the capacitor may be used in conformance with the rating and performance which are provided in both the catalog and the specifications. Use exceeding that which is specified may result in inferior performance or cause a short, open, smoking, or flaming to occur, etc.
- 2. Please consult the manufacturer in advance when the capacitor is used in devices such as: devices which deal with human life, i.e. medical devices; devices which are highly public orientated; and devices which demand a high standard of liability.
  Accident or malfunction of devices such as medical devices, space equipment and devices having to do with atomic power could generate grave consequence with respect to human lives or, possibly, a portion of the public. Capacitors used in these devices may require high reliability design different from that of general purpose capacitors.
- 3. Please use the capacitors in conformance with the operating temperature provided in both the catalog and the specifications.

  Be especially cautious not to exceed the maximum temperature. In the situation the maximum temperature set forth in both the catalog and specifications is exceeded, the capacitor's insulation resistance may deteriorate, power may suddenly surge and short-circuit may occur.

  The capacitor has a loss, and may self-heat due to equivalent series resistance when alternating electric current is passed therethrough. As this effect becomes especially pronounced in high frequency circuits, please exercise caution.

  When using the capacitor in a (self-heating) circuit, please make sure the surface of the capacitor remains under the maximum temperature for usage. Also, please make certain temperature rises remain below 20°C.
- 4. Please keep voltage under the rated voltage which is applied to the capacitor. Also, please make certain the peak voltage remains below the rated voltage when AC voltage is super-imposed to the DC voltage.
  In the situation where AC or pulse voltage is employed, ensure average peak voltage does not exceed the rated voltage.
  Exceeding the rated voltage provided in both catalog and specifications may lead to defective withstanding voltage or, in worst case situations, may cause the capacitor to smoke or flame.
- 5. When the capacitor is to be employed in a circuit in which there is continuous application of a high frequency voltage or a steep pulse voltage, even though it is within the rated voltage, please inquire to the manufacturer.
  In the situation the capacitor is to be employed using a high frequency AC voltage or a extremely fast rising pulse voltage, even though it is within the rated voltage, it is possible capacitor reliability will deteriorate.
- 6. It is a common phenomenon of high-dielectric products to have a deteriorated amount of static electricity due to the application of DC voltage.

  Due caution is necessary as the degree of deterioration varies depending on the quality of capacitor materials, capacity, as well as the load voltage at the time of operation.
- 7. Do not use the capacitor in an environment where it might easily exceed the respective provisions concerning shock and vibration specified in the catalog and specifications.
  In addition, it is a common piezo phenomenon of high dielectric products to have some voltage due to vibration or to have noise due to
- 8. If the electrostatic capacity value of the delivered capacitor is within the specified tolerance, please consider this when designing the respective product in order that the assembled product function appropriately.
- 9. Please contact us upon using conductive adhesives.

voltage change. Please contact sales in such case.

#### **Storage**

- 1. If the component is stored in minimal packaging (a heat-sealed or zippered plastic bag), the bag should be kept closed. Once the bag has been opened, reseal it or store it in a desiccator.
- 2. Keep storage place temperature +5 to +40 degree C, humidity 20 to 70% RH. See JIS C 60721-3-1, class 1K2 for other climatic conditions.
- 3. The storage atmosphere must be free of corrosive gas such as sulfur dioxide and chlorine. Also, avoid exposing the product to saline moisture. If the product is exposed to such atmospheres, the terminals will oxidize and solderability will be effected.
- 4. Precautions 1) to 3) apply to chip capacitors packaged in carrier tapes.
- 5. The solderability is assured for 6 months from our shipping date if the above storage precautions are followed.

Safety application guideline and detailed information of electrical properties are also provided in Kyocera home page; URL: http://www.kyocera.co.jp/electronic/

## **Mouser Electronics**

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